



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

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12 Mar 2009

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16231

TITLE: Copper Wire in SOT223 packaged Products

PROPOSED FIRST SHIP DATE: 12 Jun 2009

AFFECTED CHANGE CATEGORY(S): Assembly Process

AFFECTED PRODUCT DIVISION(S): Analog

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Alan Garlington <alan.garlington@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Tomas Vajter <tomas.vajter@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

A General Announcement (GA#16200) was published on 1-29-09 regarding the ongoing Copper Wirebond conversion program at ON Semiconductor. This is a FPCN to notify customers of its plan to qualify Copper Wire (in place of Gold Wire) on the IC SOT223 package assembled at the Seremban, Malaysia assembly location. Reliability Qualification and full electrical characterization over temperature has now been completed on the designated package qualification vehicles.

**Final Product/Process Change Notification #16231****RELIABILITY DATA SUMMARY:**

Test Vehicles used: NCP565ST12T3G and NCP1117STAT3G

Reliability Test Results: NCP565ST12T3G

Test	Conditions		Results
HTSL	High Temp Storage Life	Ta = 150c ; 1000 Hrs	0/168
UHASt-PC	Highly Accel. Stress Test Preconditioned	Ta = 130C, RH = 85%; 96 Hrs PSIG = 18.8, with bias	0/168
TC – PC	Temperature Cycle Preconditioned	-65C to +150C; 1000 Cycle	0/168
MSL1	SAT Testing	MSL1 Preconditioning	0/10

Reliability Test Results: NCP1117STAT3G

Test	Conditions		Results
HTSL	High Temp Storage Life	Ta = 150c; 1000 Hrs	0/168
UHASt-PC	Highly Accel. Stress Test Preconditioned	Ta = 130C, RH = 85%; 96 Hrs PSIG = 18.8, with bias	0/168
TC – PC	Temperature Cycle Preconditioned	-65C to +150C; 1000 Cycle	0/168
MSL1	SAT Testing	MSL1 Preconditioning	0/10

ELECTRICAL CHARACTERISTIC SUMMARY:

Electrical Data is available upon request.

CHANGED PART IDENTIFICATION:

Part Number Date Code with codes greater than WW 24, 2009

**Final Product/Process Change Notification #16231****AFFECTED DEVICE LIST****PART**

LM317MBSTT3G
LM317MSTT3G
MC33269ST-3.3T3G
MC33275ST-2.5T3G
MC33275ST-3.0T3G
MC33275ST-3.3T3G
MC33275ST-5.0T3G
MC33375ST-1.8T3G
MC33375ST-2.5T3G
MC33375ST-3.0T3G
MC33375ST-3.3T3G
MC33375ST-5.0T3G
MC34268STT3
NCP1117ST12T3G
NCP1117ST15T3G
NCP1117ST18T3G
NCP1117ST20T3G
NCP1117ST25T3G
NCP1117ST285T3G
NCP1117ST33T3G
NCP1117ST50T3G
NCP1117STAT3G
NCP565ST12T3G
NCP566ST12T3G
NCP566ST18T3G
NCP566ST25T3G
NCV1117ST12T3
NCV1117ST12T3G
NCV1117ST15T3G
NCV1117ST18T3G
NCV1117ST20T3
NCV1117ST20T3G
NCV1117ST25T3G
NCV1117ST33T3G
NCV1117ST50T3G
NCV1117STAT3G
NCV2931AST-5T3G
NCV33275ST3.3T3G
NCV33275ST-5.0T3
NCV33275ST5.0T3G
NCV33375ST1.8T3G
SCY33275ST-3.3T3